

Application Stability of Fast Switching Planar SiC MOSFETs

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Alpha and Omega Semiconductor*

**Bodo's
Wide Bandgap
Event 2024**

Making WBG Designs Happen

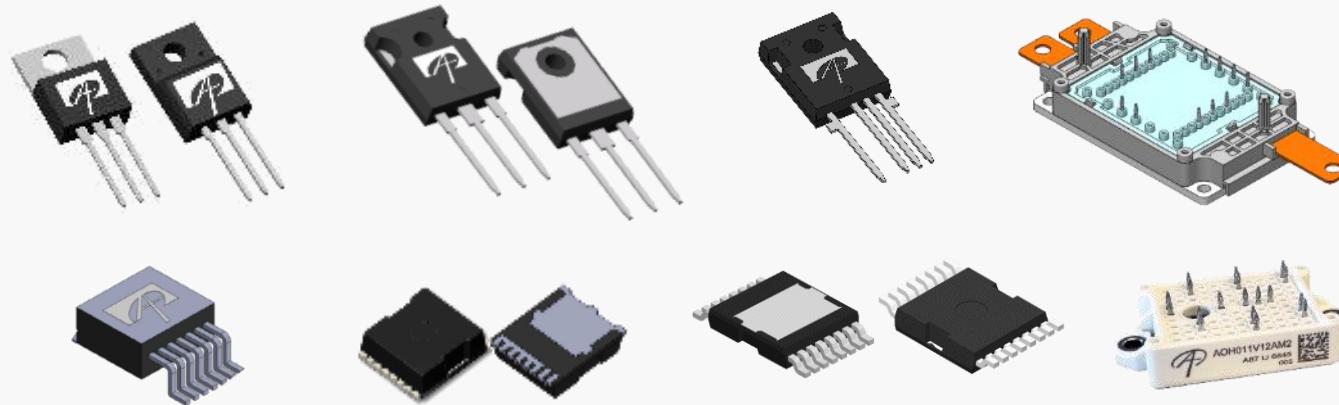
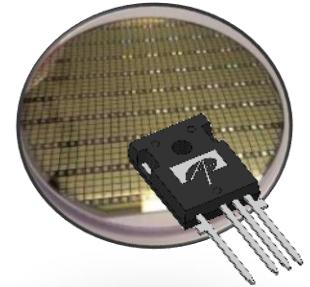
SiC

AOS / Silicon Carbide Introduction



• Alpha and Omega Semiconductor (AOS)

- Headquarters: Sunnyvale, CA
- Global Employees: 2500
- 8" and 12" In-house IATF16949
- Si Discrete Power Fabs
- Si MOSFETs, IGBT, SJ-MOS, PIC, WBG
- Leading 5th MOSFET supplier WW (2021)
- 2 In-house IATF16949 discrete/module assy & test locations



650V, 750V, 1200V, 1700V
15mΩ – 500mΩ

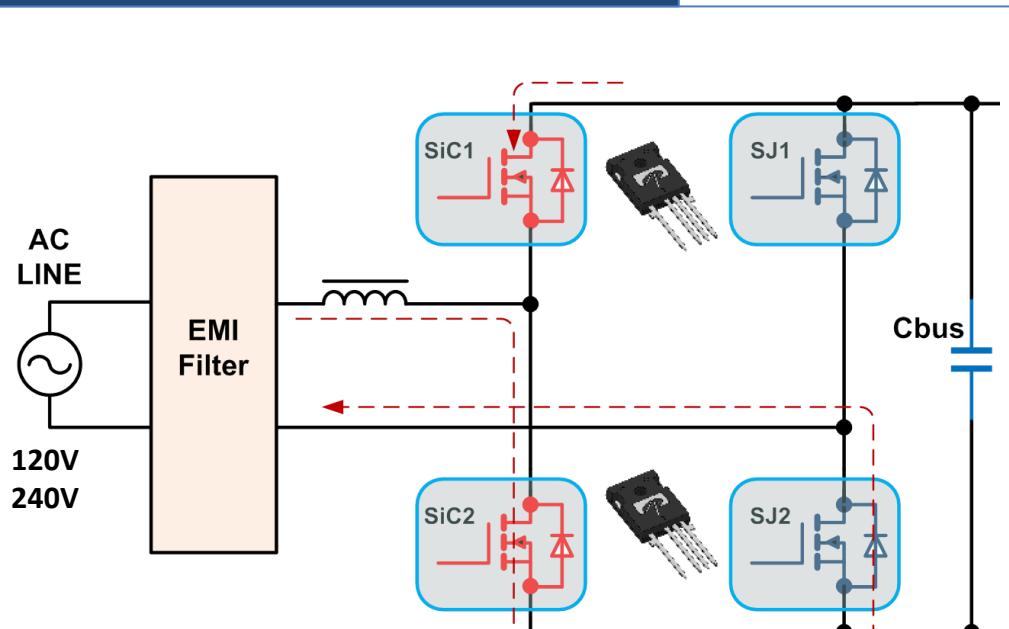


General SiC Applications

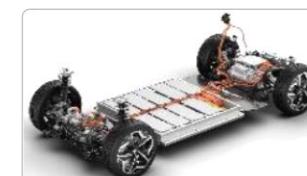
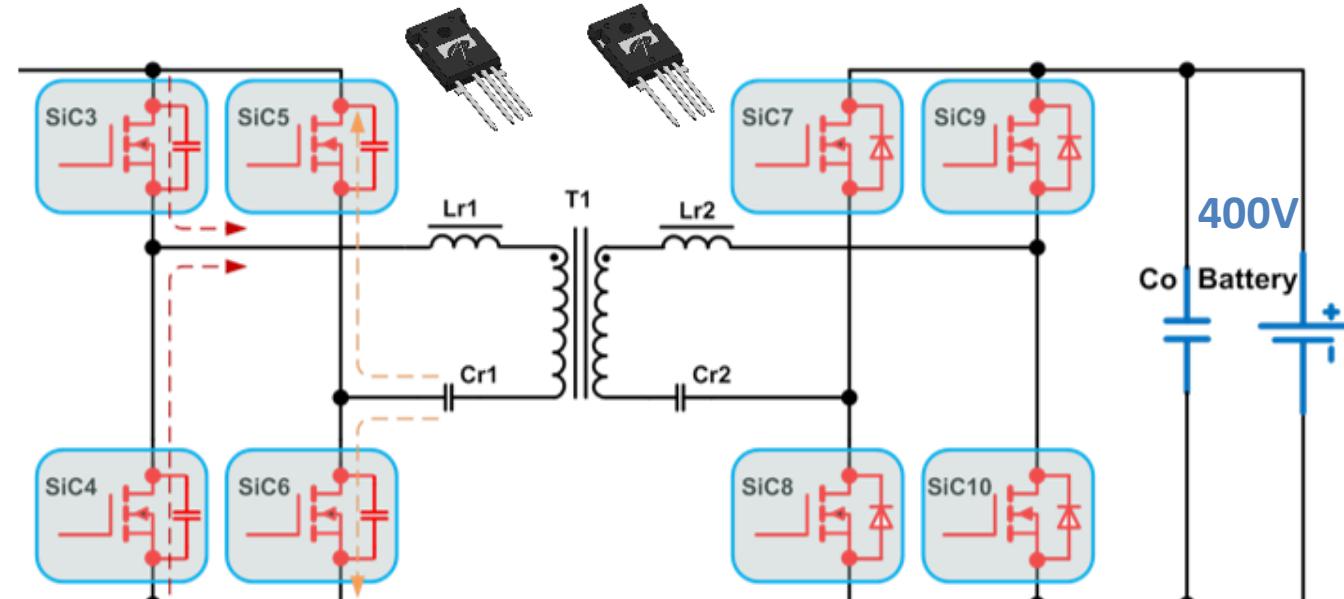


□ Industrial and Automotive Applications: Solar, Server/Telecom, Auto OBC - Inverter

Hard Switching: Totem-Pole PFC



Resonant: CLLC, DAB, CLLLC, Etc.



High Efficiency Hard Switching Applications



Question: Can I switch a SiC MOSFET at $V_{GS,off}=0V$ drive conditions?

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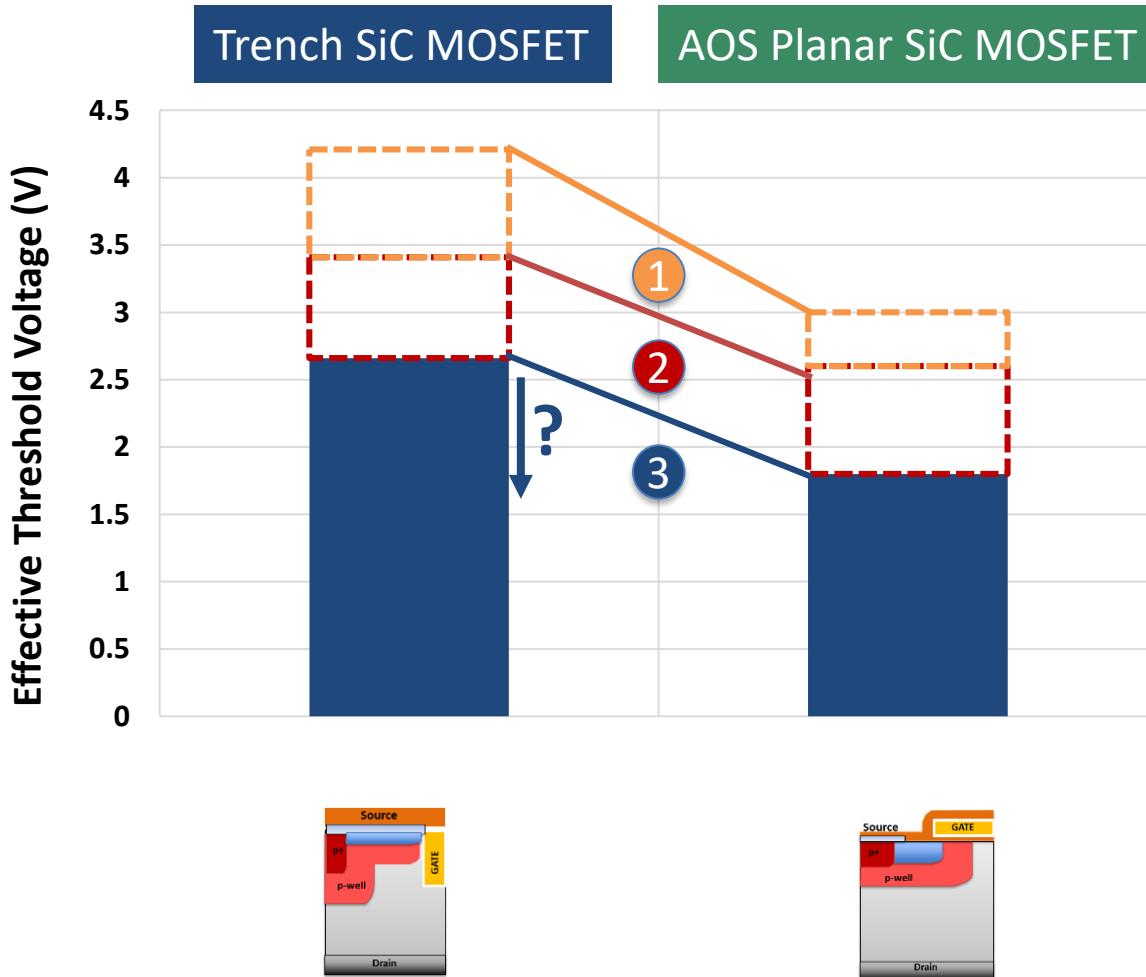
Answer: Maybe

Considerations:

- **SiC MOSFET Characteristics**
 - C_{GS}/C_{GD}
 - Threshold voltage
- **Gate Driver**
 - Miller clamp
- **Circuit and Application Conditions**
 - Hard Switching
 - Driving dV/dt
 - Gate/Source loop inductances
 - Layout design

What is Threshold Voltage in Application?

- In Practice, Datasheet V_{th} can be different

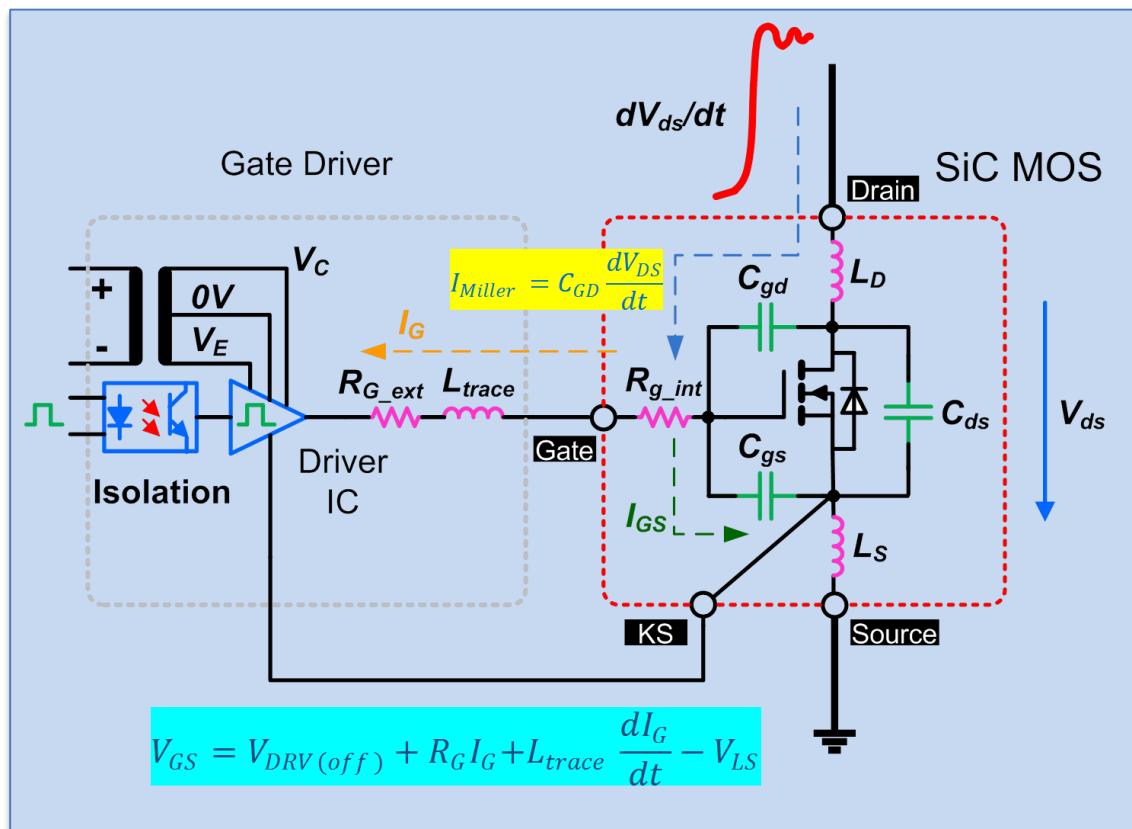


- ① **DIBL affect static V_{th} at high voltage**
 - Drain bias reduces channel barrier
 - Less V_{GS} required to turn on device
- ② **V_{th} reduces at high temperature**
 - Simple device physics
 - Lowering of barrier with T
- ③ **Switching reduces effective V_{th} at high dV/dt**
 - Classic shoot-through circuit dynamics
 - Internal R_G , C_{GS} , C_{GD} , starting V_{TH}

1200V SiC MOSFETs: Shoot-Through Testing

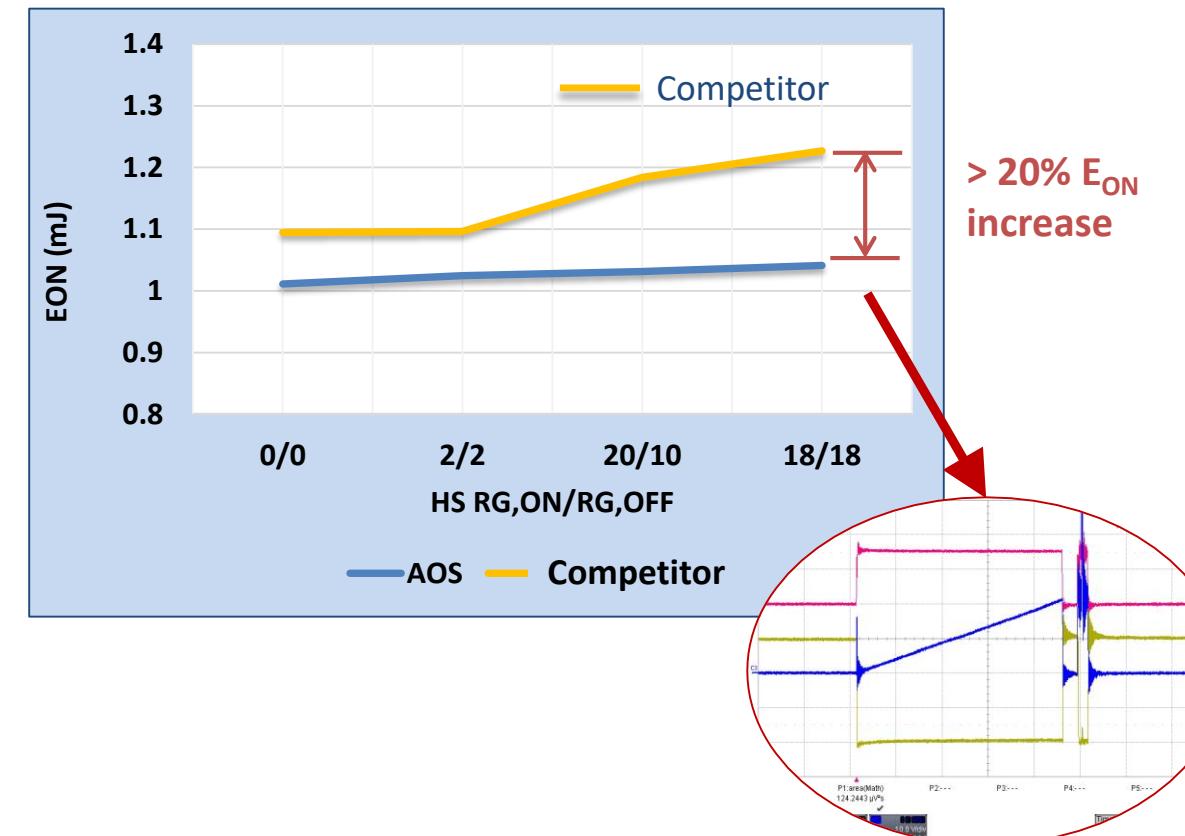


Switching reduces effective V_{th} at high dV/dt



Measure E_{ON} of LS device with HS variable $R_{G,OFF}$

- $V_{DC}=800V$, $I_D=40A$, upper switch $V_{gs}=0V$
- $dV/dt \sim 80V/ns$

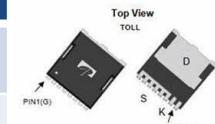
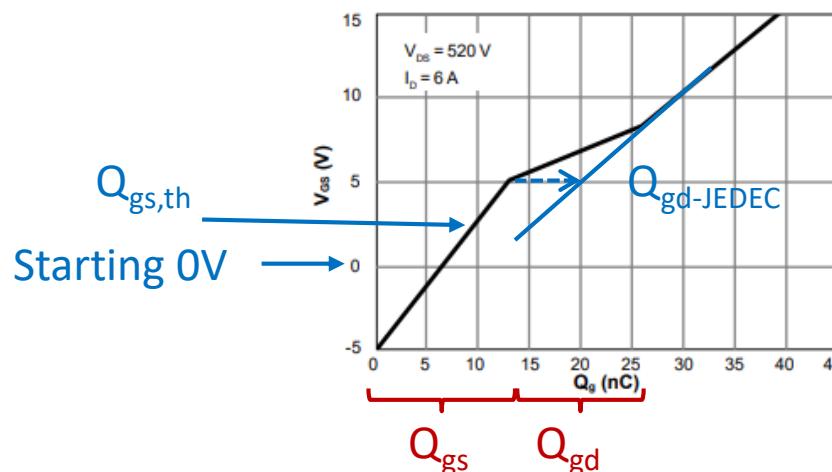


650V MOSFETs / Double Pulse Shoot-Through Test

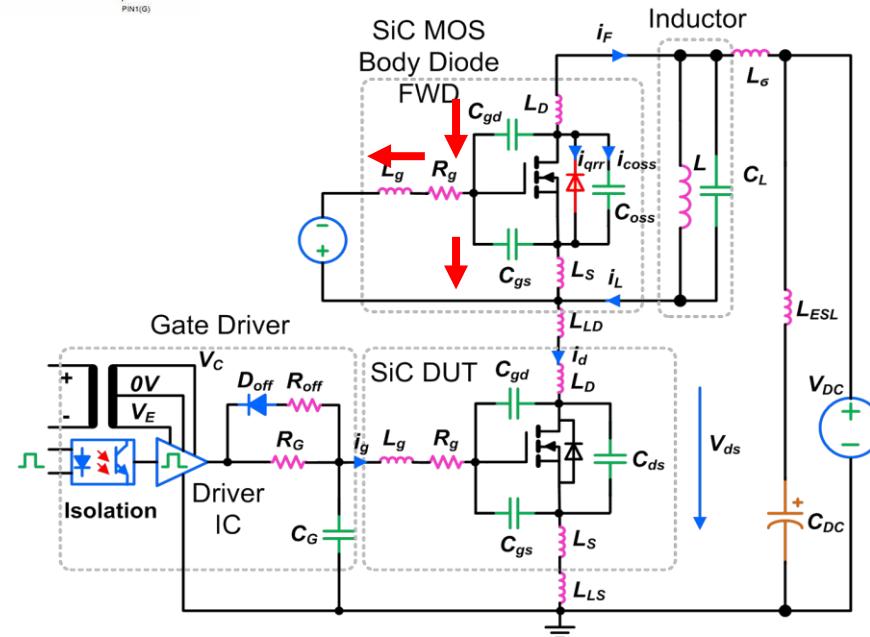


- 650V Datasheet Important Parameters
→ Qg: Not all measured the same

SiC MOSFET	V _{TH} (V)	Q _{gs} (nC)	Q _{gs,th} (nC)	Q _{gd} (nC)	Q _{gd-JEDEC} (nC)	R _{G,INT} (Ω)	FOM
AOS Planar	2.8	5	1.7	12.9	8	2.2	.56
Trench	4.5	5	3	12.5	3.5	5.1	.76
Trench	4.5	11	10	19	10	12	.38
Planar	2.3	7	2	17	12.5	3	.12
Planar	2.9	10	4.5	16	14	5	.19



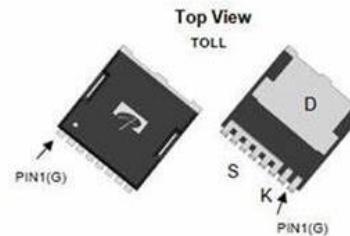
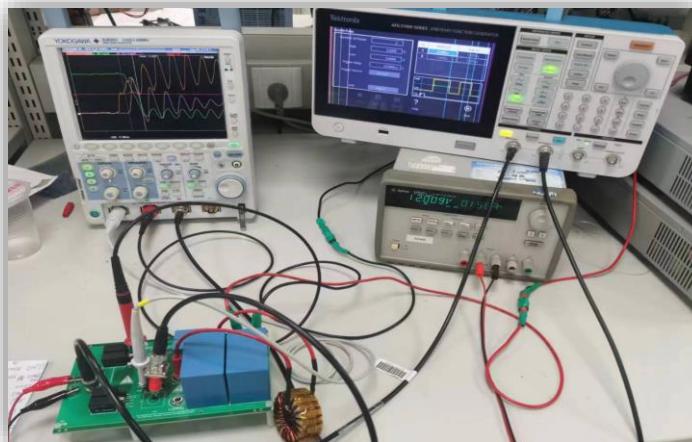
$$\text{Rough FOM} = \frac{V_{TH} \times \frac{Q_{gd}}{Q_{gs}}}{R_{G,INT}}$$



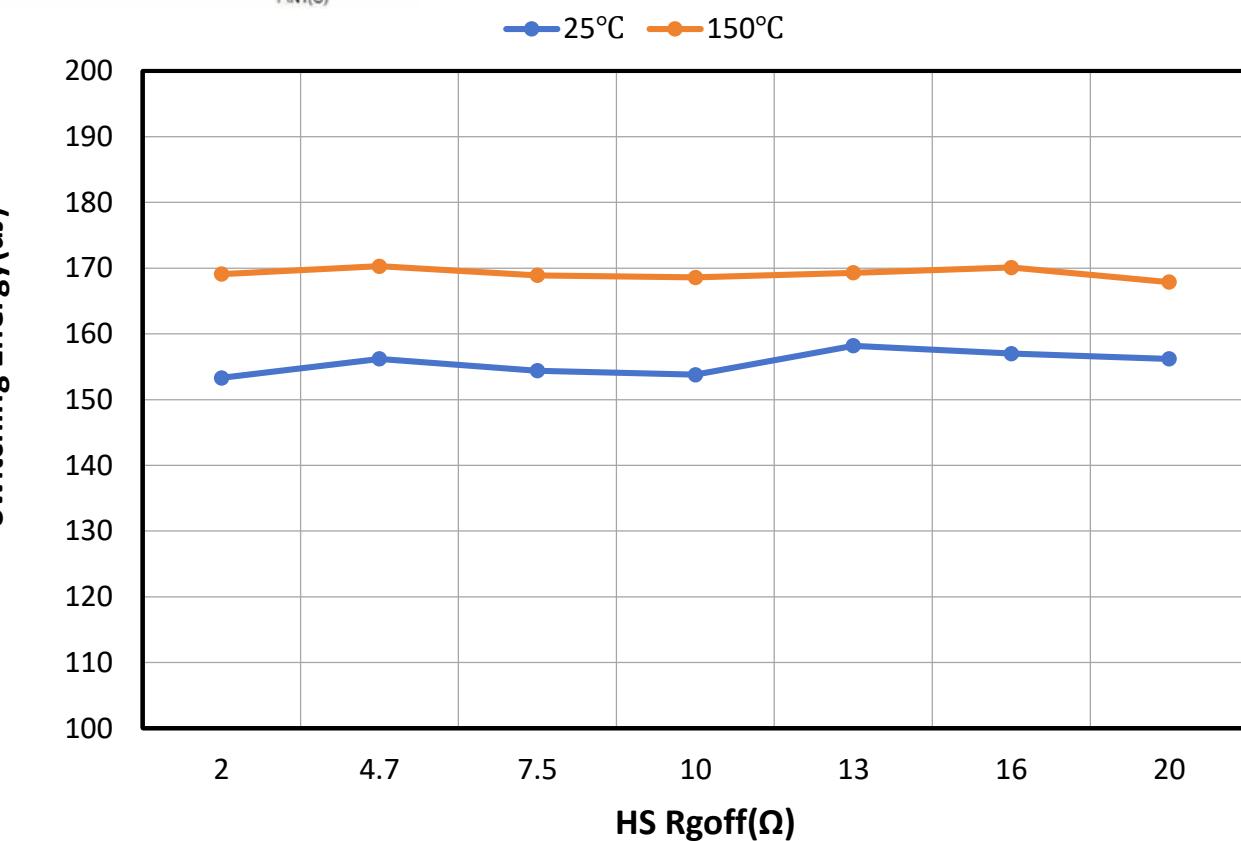
650V Double Pulse Shoot-Through Test

- Test AOS Device Under Worst Case Device Conditions

Test Conditions		
Bus voltage V_{DC}	400V	500V
Junction Temp. T_j	25°C	150°C
Switching dv/dt	42V/ns	84.4V/ns
HS Gate Off Resistance $R_{goff(HS)}$	2~20Ω	2~20Ω
LS Gate On Resistance $R_{gon(LS)}$	2Ω	2Ω
Drain-Source Current I_D	40A	40A
HS&LS Gate Voltage	0/+18V	0/+18V



LS Eon vs HS Rgoff



650V SiC Cross-Conduction Burn-in Test

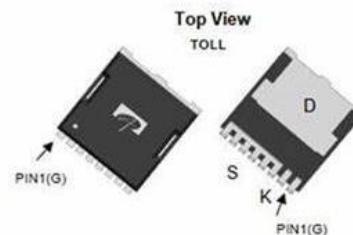


Test Set-up and Topology

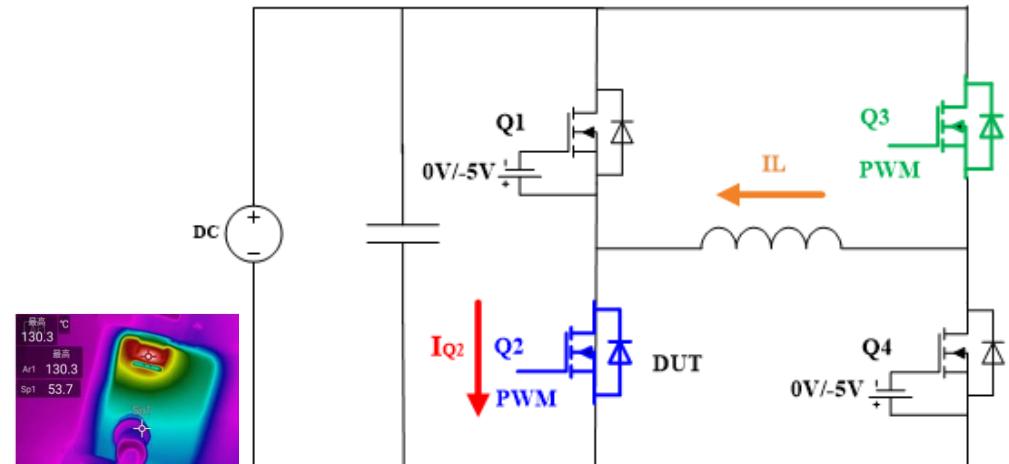
- Burn-in test is used to simulate the real working condition of SiC MOSFET with 0V turn-off voltage in application.

Conditions

Bus voltage V_{DC}	500V
Peak Current I_{DM}	50A
System Switching Frequency F_S	10kHz
HS&LS Gate Voltage	0/+18V
HS Gate Off Resistance $R_{goff(HS)}$	20Ω
LS Gate On Resistance $R_{gon(LS)}$	2Ω
Junction Temp. T_j	150°C



Burn-in Topology

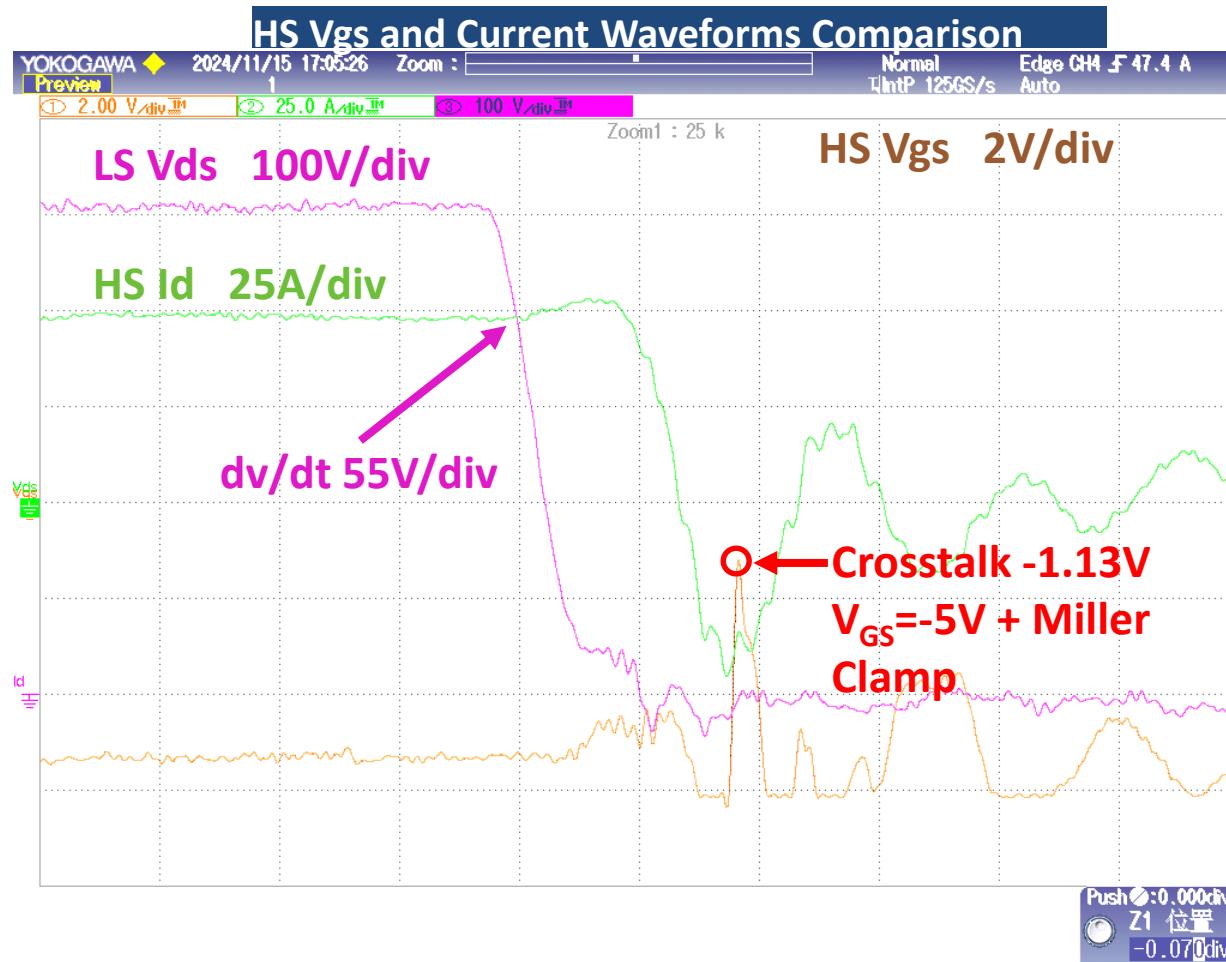


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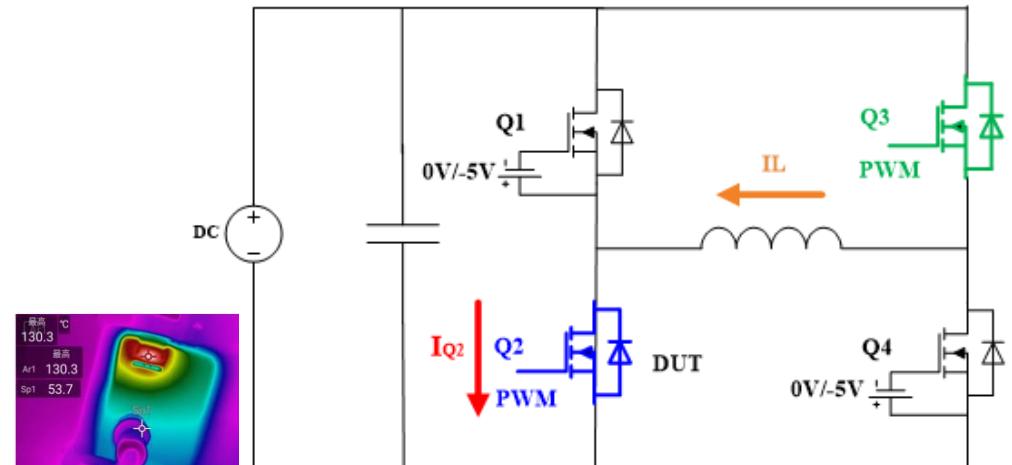


Benchmark test:

- $V_{DS}=500V$, $T_j=150C$, $dV/dt=55V/ns$
- $V_{GS}=-5V + \text{Miller Clamp} \rightarrow \text{Baseline Current}$



Burn-in Topology

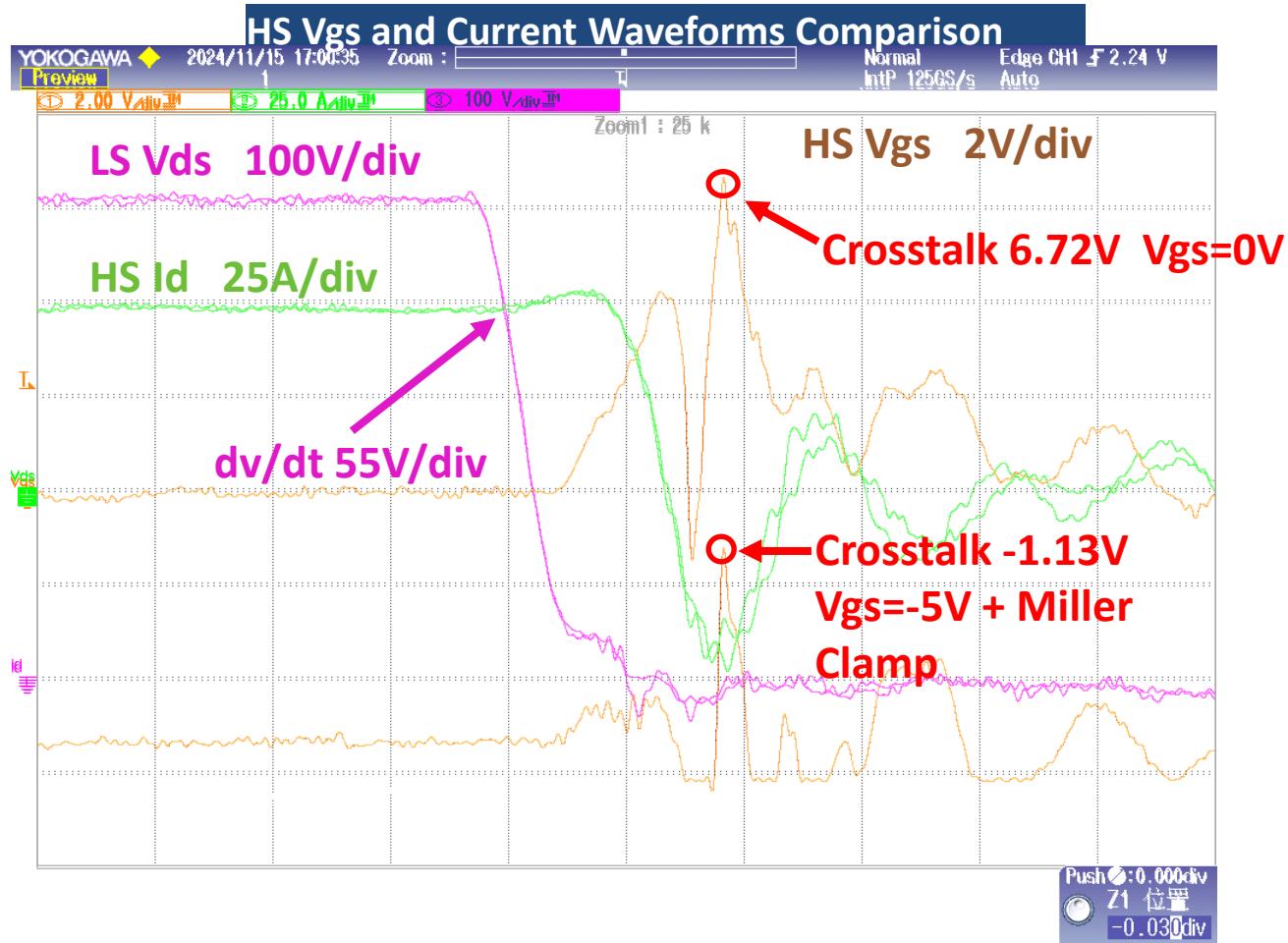


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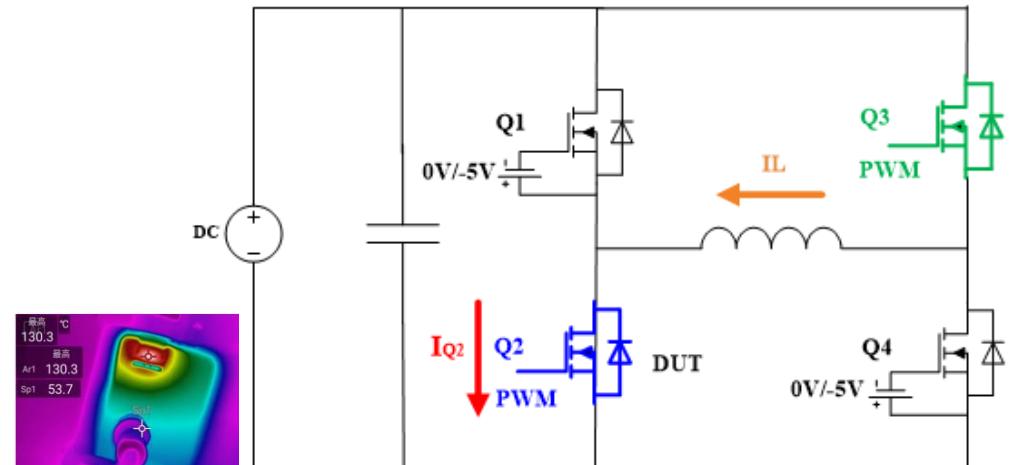


- Benchmark test:

- $V_{DS}=500V$, $T_j=150C$, $dV/dt=55V/ns$
- $V_{GS}=0V \rightarrow$ No Change in Current! = No shoot-through!



Burn-in Topology





Question: Can I switch a SiC MOSFET at $V_{GS,off}=0V$ drive conditions?

Answer: Yes!

- Use optimized SiC MOSFET with low $R_{G,int}$, Good Q_{gs}/Q_{gd} , higher V_{TH} , Low DIBL
- Optimized Layout
- Manage dV/dt
- Gate Driver with Miller Clamp
- Evaluate over worst case conditions

Thank You!